

METHOD OF FORMING CONDUCTOR WIRING PATTERN

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ABSTRACT OF THE DISCLOSURE

10 A method of forming a conductor wiring pattern  
comprises: forming a first insulating layer on a surface  
of a semiconductor wafer and also forming a second,  
photosensitive insulating resin layer thereon; light-  
exposing and developing the second insulating layer to  
form pattern grooves so that the first insulating layer  
is exposed at bottoms of the pattern grooves; forming a  
15 plating seed layer on the second insulating layer  
including inner surfaces of the pattern grooves and then  
forming a resist pattern on the seed layer except for  
portions of the pattern grooves; filling the pattern  
grooves with a conductor by an electrolytic plating using  
20 the seed layer as a power supply layer; and removing the  
resist pattern and also removing the seed layer exposed  
on the surface of the second insulating layer to form a  
wiring pattern consisting of conductors remaining in the  
pattern grooves.